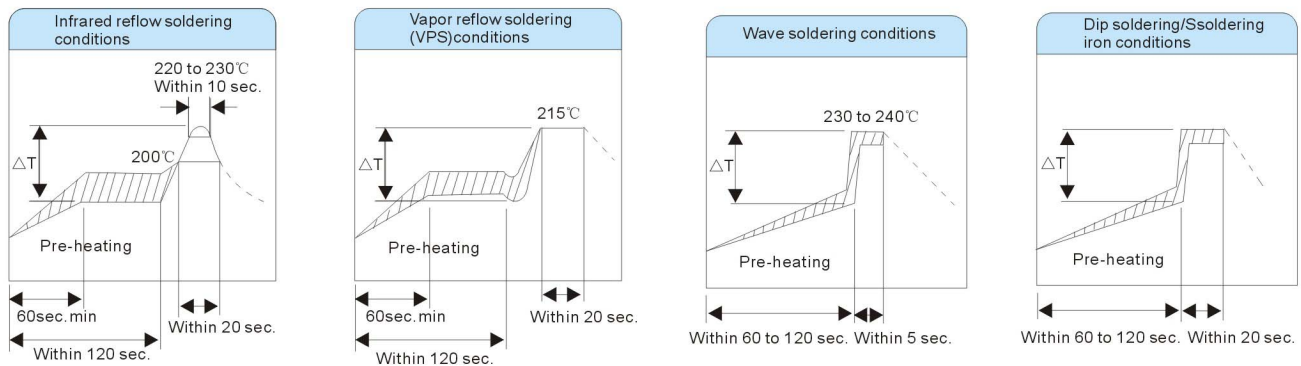


Advised Soldering Profile (Prevention of thermal shock)



NOTES:

- Carefully perform pre-heating so that the temperature difference (ΔT) between the color and component surface should be within the range.
- Do not allow the iron-tip to directly touch the ceramic element.

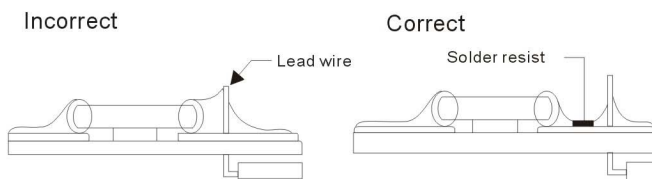
ΔT	Chip size
120°C	3.2 × 1.6mm max

PCB Design

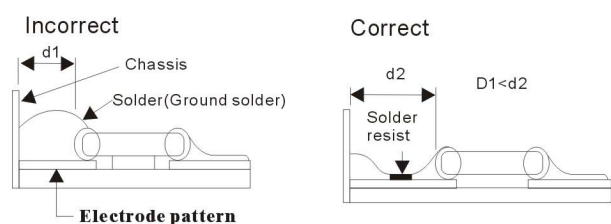
Chip components are susceptible to board stress since the component itself is mounted directly on the board. They are also sensitive to mechanical and thermal stress when solder, which may cause chip cracked. Please take solder from and component layout into consideration to eliminate stress.

Pattern Form

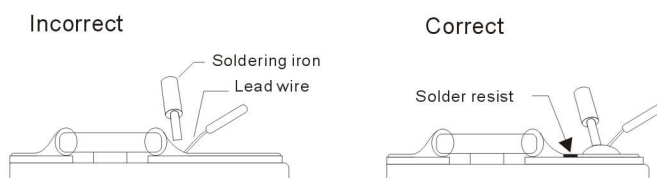
Placing of chip components and component.



Placing of close to chassis.



Placing leaded components after chip component.



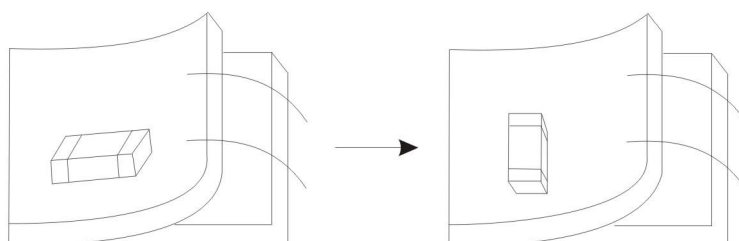
Lateral mounting



Component Direction

To design a mounting position that minimizes the stress imposed on the chip during flexing or bending of the board.

Put the component lateral to the direction in which stress acts.



Component layout close to board separation point. Susceptibility to stress in the order: A > C > B = D

